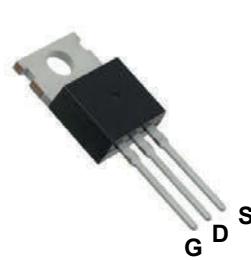
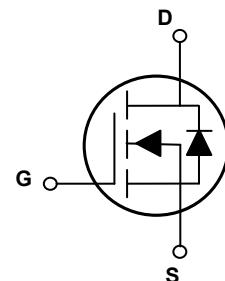


## Main Product Characteristics

$V_{(BR)DSS}$	200V
$R_{DS(ON)}$	49mΩ (max.)
$I_D$	24A



TO-220



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFH49020 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	24	A
Continuous Drain Current, @ Steady-State ( $T_C=100^\circ\text{C}$ )		15	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	96	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	150	W
Linear Derating Factor ( $T_C=25^\circ\text{C}$ )		1.2	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	29	mJ
Junction-to-Case	$R_{\theta JC}$	0.83	$^\circ\text{C}/\text{W}$
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	200	-	-	V
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
		$T_J=125^\circ\text{C}$	-	-	20	
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}$	-	-	100	$\text{nA}$
		$V_{\text{GS}}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=22\text{A}$	-	41.6	49	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	2.1	3	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}$ $F=1\text{MHz}$	-	1223	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	94	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	6.8	-	
Total Gate Charge	$Q_g$	$I_D=12\text{A}, V_{\text{DS}}=100\text{V},$ $V_{\text{GS}}=10\text{V}$	-	20.5	-	$\text{nC}$
Gate-to-Source Charge	$Q_{\text{gs}}$		-	8.6	-	
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		-	4.8	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=100\text{V},$ $I_D=12\text{A}, R_{\text{GEN}}=6\Omega$	-	11.5	-	$\text{nS}$
Rise Time	$t_r$		-	26.3	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	34.5	-	
Fall Time	$t_f$		-	22.6	-	
Gate Resistance	$R_g$		$F=1\text{MHz}$	-	1.8	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	24	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$		-	-	96	A
Diode Forward Voltage	$V_{\text{SD}}$	$I_s=24\text{A}, V_{\text{GS}}=0\text{V}$	-	1	1.2	V
Reverse Recovery Time	$T_{\text{rr}}$	$T_J=25^\circ\text{C}, I_F=24\text{A},$ $di/dt=100\text{A}/\mu\text{s}$	-	83	-	$\text{ns}$
Reverse Recovery Charge	$Q_{\text{rr}}$		-	0.3	-	

Note:

1. Pulse test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $L=0.1\text{mH}, V_{\text{DD}}=80\text{V}, I_{\text{AS}}=24\text{A}, T_J=25^\circ\text{C}$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Typical Electrical and Thermal Characteristic Curves

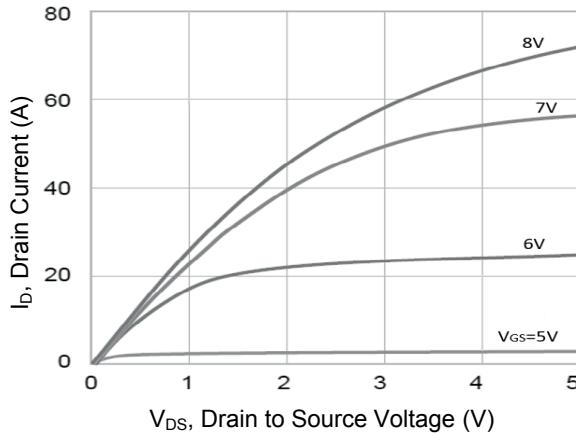


Figure 1. Output Characteristics

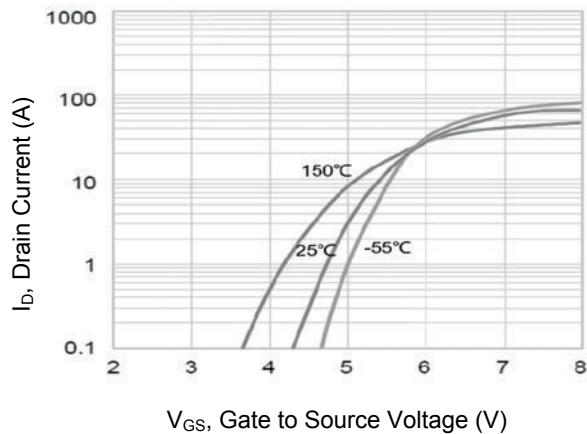


Figure 2. Transfer Characteristics

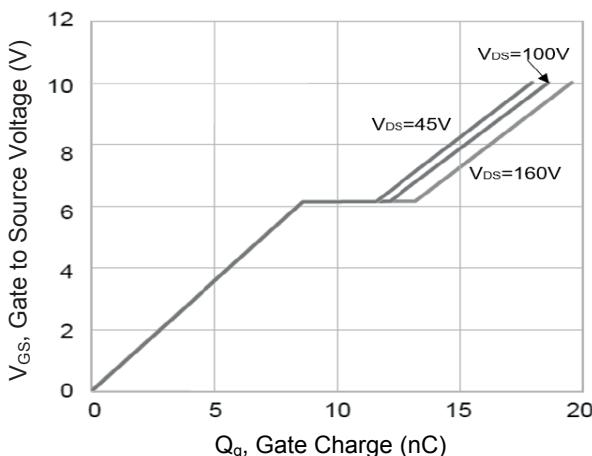


Figure 3. Gate Charge

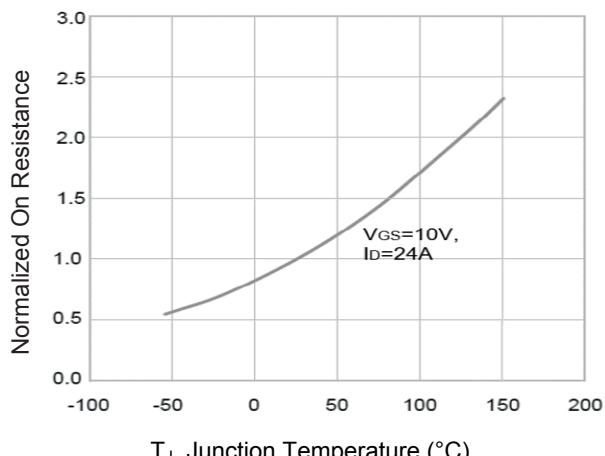


Figure 4. Normalized  $R_{DS(on)}$  vs. Junction Temperature

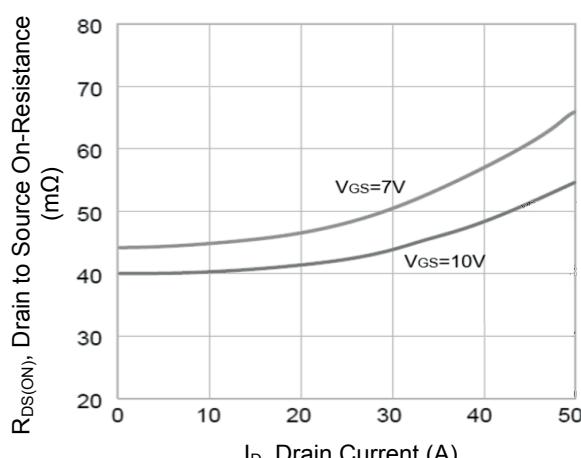


Figure 5. On-Resistance vs. Drain Current

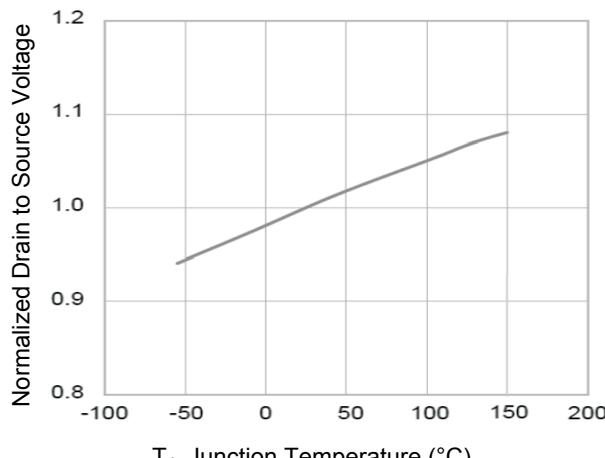
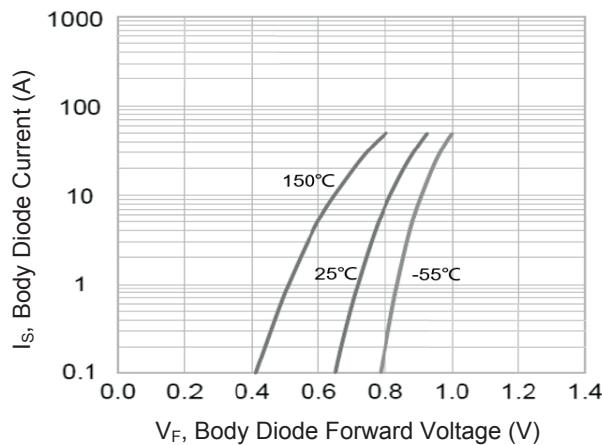
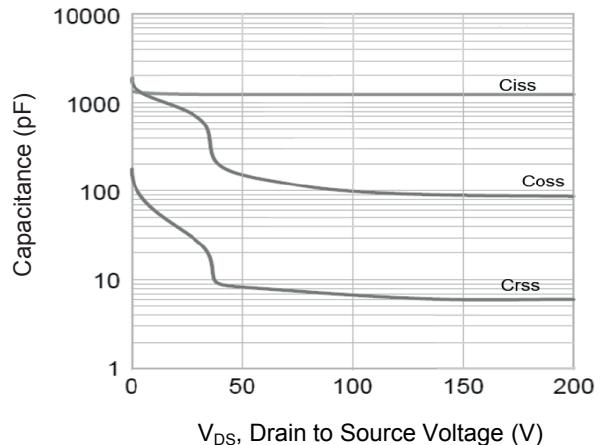


Figure 6. Normalized  $BV_{DSS}$  Vs. Junction Temperature

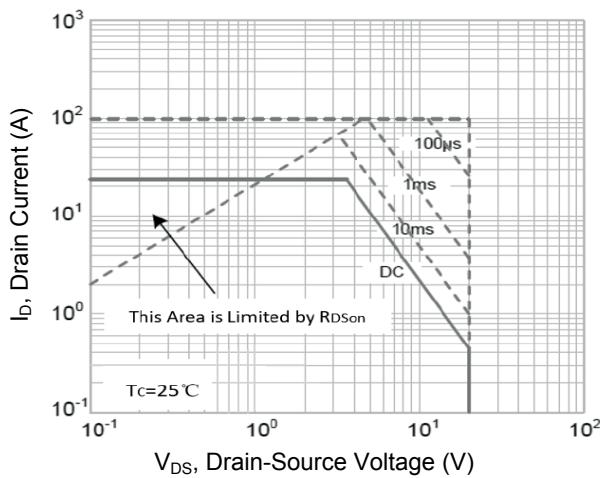
### Typical Electrical and Thermal Characteristic Curves



**Figure 7. Body Diode Characteristics**

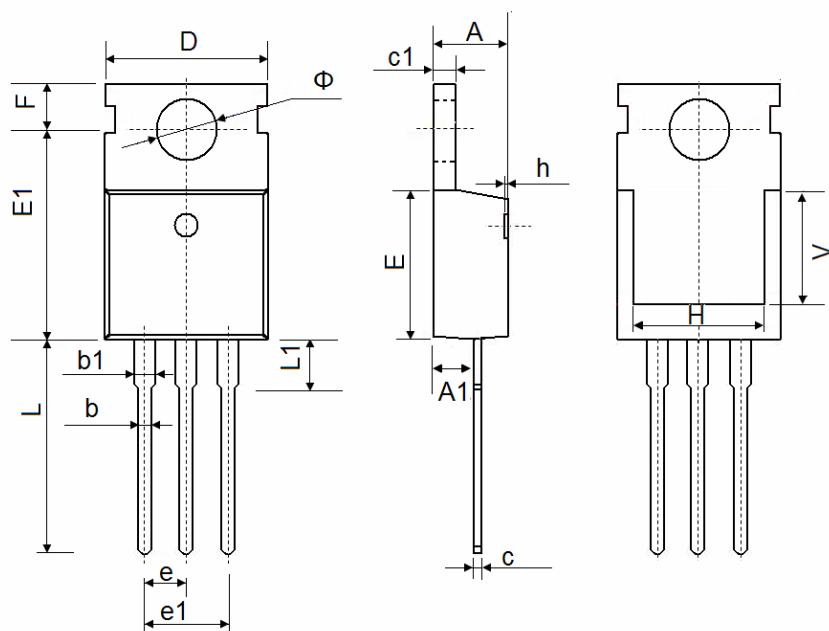


**Figure 8. Transfer Characteristics**



**Figure 9. Safe Operation Area**

**Package Outline Dimensions (TO-220)**



<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150